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ITEH09041C6

40W,28V Plastic RF LDMOS Transistor

Description

The ITEH09041C6 is a dual path 40-watt, highly rugged, LDMOS transistor, designed for driver applications at frequencies from 0.7 to 1.0GHz, in 10*6mm QFN plastic package, supporting surface mounted on PCB through high density grounding vias.

It can be configured as highly compact Doherty ,ideal for high efficiency and low cost, DPD friendly driver for 4G/5G application within 0.7-1.0GHz.

Typical 700MHz Doherty RF Performance (On Innogration fixture with device soldered). Vds=28V ldq main=30mA, Vgs peak=1.6V

Eroa	Pulse CW Signal			P _{avg} =36dBm WCDMA Signal		
Freq (MHz)	P1dB Gain (dB)	P3dB (W)	Eff@P3dB (%)	Gp (dB)	Eff(%)	ACPR _{5M} (dBc)
758	13.8	45.0	65.2	14.3	43.5	-29.6
780	14.43	46.0	67.4	15.0	43.4	-29.6
803	14.56	42.8	66.7	15.1	41.4	-29.9

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- **Suitable Applications**
- P band power ampliifer
- All 4G/5G cellular application within 0.7 to 1.0GHz
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- · Pb-free, RoHS-compliant

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+65	Vdc
GateSource Voltage	V_{GS}	-10 to +10	Vdc
Operating Voltage	V_{DD}	+28	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc	0.45	°C/W
T _C = 85°C, T _J =200°C, DC test		0.45	

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

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Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

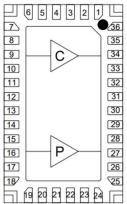
Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics					
Drain-Source Voltage	.,		0.5		V
V _{GS} =0, I _{DS} =100uA	V _{(BR)DSS}		65		V
Zero Gate Voltage Drain Leakage Current				1	
(V _{DS} = 28V, V _{GS} = 0 V)	DSS			Į	μΑ
GateSource Leakage Current	,			1	^
$(V_{GS} = 11 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}			l l	μΑ
Gate Threshold Voltage	V (II)		2		V
$(V_{DS} = 28V, I_D = 600 \mu A)$	V _{GS} (th)		2		V
Gate Quiescent Voltage	$V_{\text{GS}(Q)}$		2.7		V
(V _{DD} = 28V, I _D = 180mA, Measured in Functional Test)					V

Load Mismatch (In Innogration Test Fixture, 50 ohm system): $V_{DD} = 28 V dc$, $I_{DQ} = 180 \text{ mA}$, f = 2200 MHz

VSWR 10:1 at 40W pulse CW Output Power No Device Degradation

Figure 1: Pin Connection definition

Transparent top view (Backside grounding for source)



Pin No.	Symbol	Description			
8,9,10,11	RF IN/Vgs1	RF Input, Vgs bias for main path			
14,15,16,17	RF IN/Vgs2	RF Input, Vgs bias for peak path			
32,33,34,35	RF OUT/VDD1	RF Output, VDD bias for Main path			
26,27,28,29	RF OUT/VDD2	RF Output, VDD bias for Peak path			
Rest pins	NC	No connection			
2,5,7,12,13,18,20,23,25,30,31,36,	CND	DC/RF Ground. Must be soldered directly to heatsink or copper coin for			
Package Base GND		CW application.			



758-803MHz application board

Reference Circuit of Test Fixture Assembly Diagram 20mils RO4350B

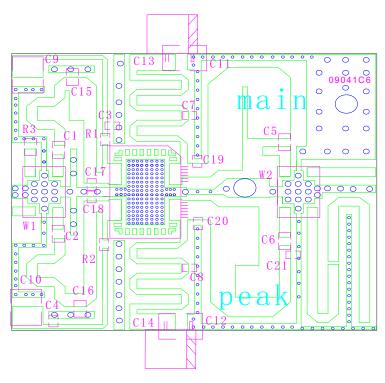


Figure 2. Test Circuit Component Layout

Table 5. Test Circuit Component Designations and Values

Designator Comment **Footprint** Quantity C1, C2, 0402/0603 2 10pF C3, C4, C5, C6, C7, C8 0402/0603 6 68pF C9, C10, C11, C12 10uF/100V 4 1210 C13, C14 100uF/63V 2 C15 8.2pF 0402/0603 1 C16 6.8pF 0402/0603 1 0402/0603 2 C17, C18 18 pF 0402/0603 C19 1.0pF 1 0402/0603 C20 4.7pF 1 0402/0603 C21 2.0pF 1 R1, R2 10 Ω 0402/0603 2 51 Ω R3 0805 1 2 W1, W2 HC07F03



TYPICAL CHARACTERISTICS

Figure 5. Power Gain and Drain Efficiency as function of Power Output at Idq=180mA

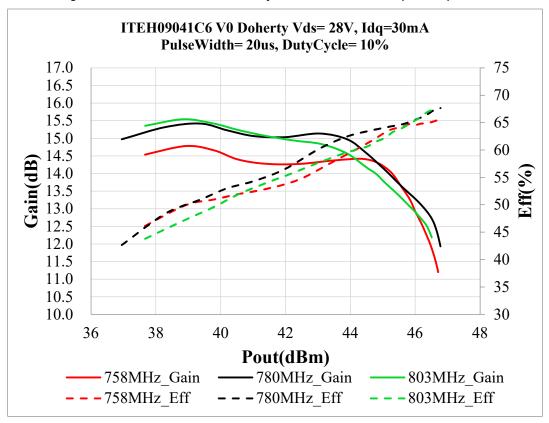
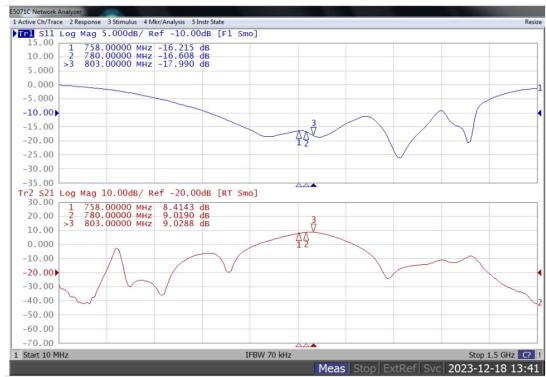


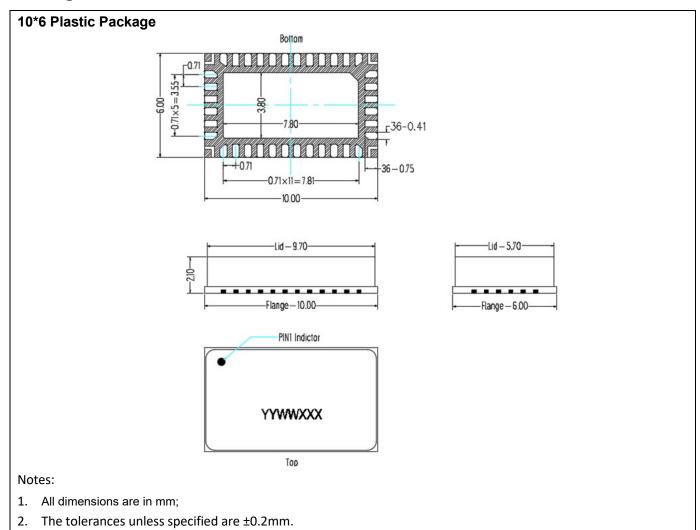
Figure 5.Network analyzer output S11/S21



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Package Dimensions



Revision history

Table 7. Document revision history

Date	Revision	Datasheet Status
2023/12/18	Rev 1.0	Preliminary Datasheet

Application data based on LSM-23-38

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